

DAP222, DAP202U

Preferred Device

Common Anode Silicon Dual Switching Diodes

These Common Anode Silicon Epitaxial Planar Dual Diodes are designed for use in ultra high speed switching applications. The DAP222 device is housed in the SC-75/SOT-416 package which is designed for low power surface mount applications, where board space is at a premium. The DAP202U device is housed in the SC-70/SOT-323 package.

Features

- Fast t_{rr}
- Low C_D
- Available in 8 mm Tape and Reel
- Pb-Free Package is Available

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	80	Vdc
Peak Reverse Voltage	V_{RM}	80	Vdc
Forward Current	I_F	100	mAdc
Peak Forward Current	I_{FM}	300	mAdc
Peak Forward Surge Current	$I_{FSM}(1)$	2.0	Adc

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

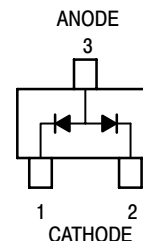
THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation	P_D	150	mW
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 ~ +150	$^\circ\text{C}$

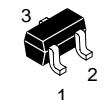


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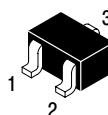
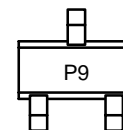
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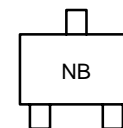
MARKING DIAGRAMS



SC-75
CASE 463
STYLE 3



SC-70
CASE 419



ORDERING INFORMATION

Device	Package	Shipping†
DAP222	SC-75	3000/Tape & Reel
DAP202U	SC-70	3000/Tape & Reel
DAP222T1	SC-75	3000/Tape & Reel
DAP222T1G	SC-75 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Characteristic	Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current	I_R	$V_R = 70\text{ V}$	—	0.1	μA dc
Forward Voltage	V_F	$I_F = 100\text{ mA}$	—	1.2	Vdc
Reverse Breakdown Voltage	V_R	$I_R = 100\text{ }\mu\text{A}$	80	—	Vdc
Diode Capacitance	C_D	$V_R = 6.0\text{ V}, f = 1.0\text{ MHz}$	—	3.5	pF
Reverse Recovery Time	DAP222 $t_{rr}(2)$ DAP202U $t_{tr}(3)$	$I_F = 5.0\text{ mA}, V_R = 6.0\text{ V}, R_L = 100\text{ }\Omega, I_{rr} = 0.1 I_R$ $I_F = 5.0\text{ mA}, V_R = 6.0\text{ V}, R_L = 50\text{ }\Omega, I_{rr} = 0.1 I_R$	— —	4.0 10.0	ns

- $t = 1\text{ }\mu\text{s}$
- t_{rr} Test Circuit for DAP222 in Figure 4.
- t_{tr} Test Circuit for DAP202U in Figure 5.

TYPICAL ELECTRICAL CHARACTERISTICS

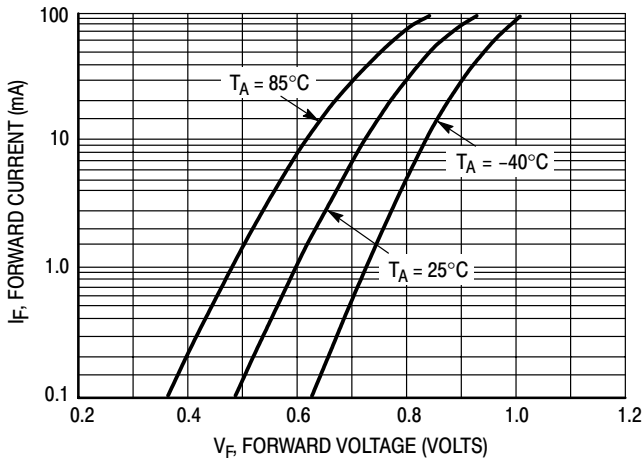


Figure 1. Forward Voltage

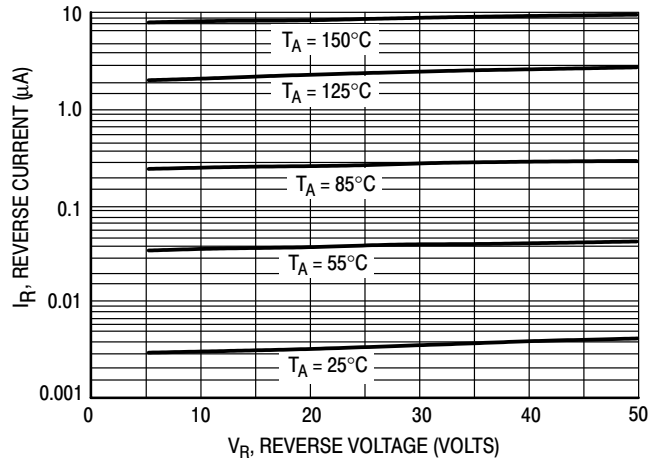


Figure 2. Reverse Current

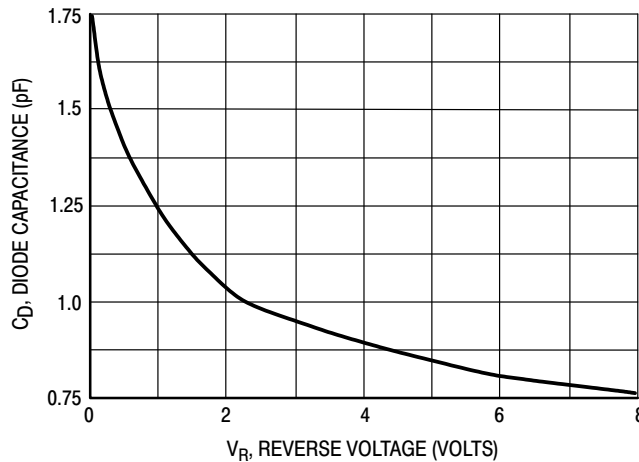
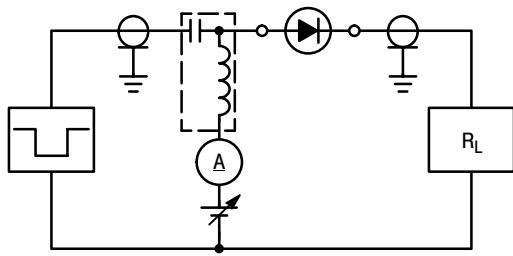
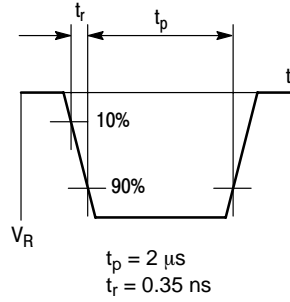


Figure 3. Diode Capacitance

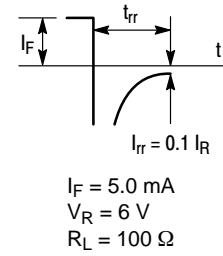
DAP222, DAP202U



RECOVERY TIME EQUIVALENT TEST CIRCUIT

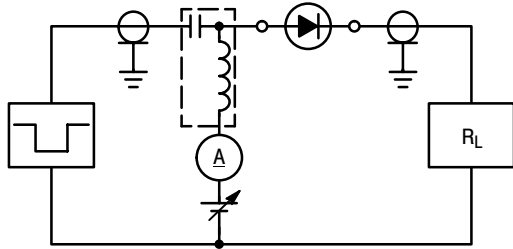


INPUT PULSE

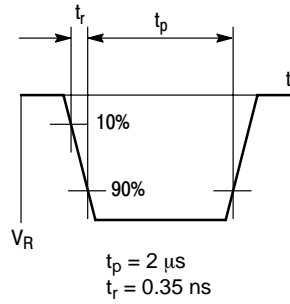


OUTPUT PULSE

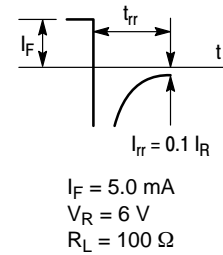
Figure 4. Reverse Recovery Time Test Circuit for the DAP222



RECOVERY TIME EQUIVALENT TEST CIRCUIT



INPUT PULSE



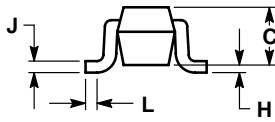
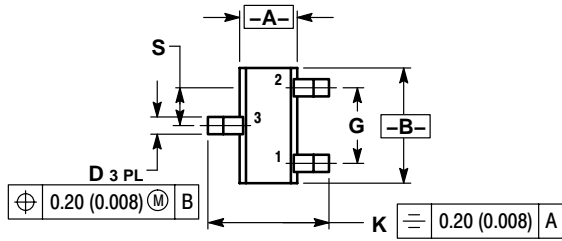
OUTPUT PULSE

Figure 5. Reverse Recovery Time Test Circuit for the DAP202U

DAP222, DAP202U

PACKAGE DIMENSIONS

SC-75 (SOT-416)
CASE 463-01
ISSUE C



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
B	1.40	1.80	0.055	0.071
C	0.60	0.90	0.024	0.035
D	0.15	0.30	0.006	0.012
G	1.00 BSC		0.039 BSC	
H	---	0.10	---	0.004
J	0.10	0.25	0.004	0.010
K	1.45	1.75	0.057	0.069
L	0.10	0.20	0.004	0.008
S	0.50 BSC		0.020 BSC	

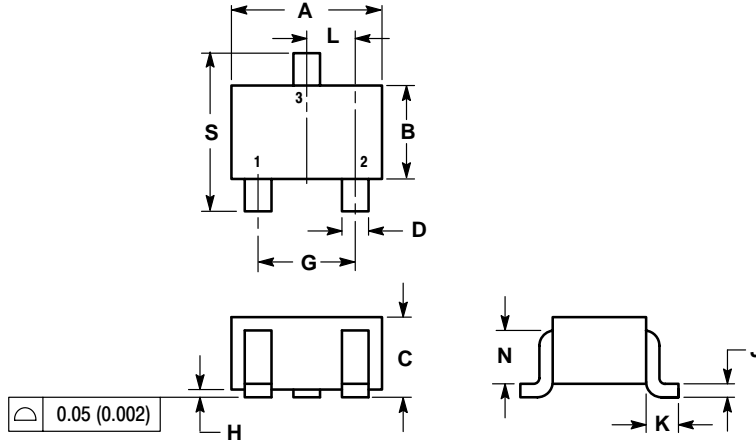
STYLE 3:

1. ANODE
2. ANODE
3. CATHODE

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PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE L

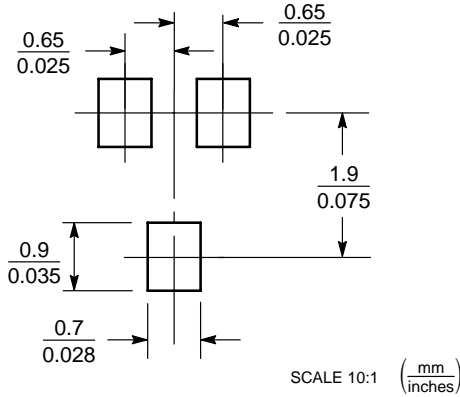


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.032	0.040	0.80	1.00
D	0.012	0.016	0.30	0.40
G	0.047	0.055	1.20	1.40
H	0.000	0.004	0.00	0.10
J	0.004	0.010	0.10	0.25
K	0.017 REF		0.425 REF	
L	0.026 BSC		0.650 BSC	
N	0.028 REF		0.700 REF	
S	0.079	0.095	2.00	2.40

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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